Texas Instruments Inc. (DUNS# 00-732-1904) Supplier Name:

Contact Info:

ti.com/support
Distribute - RoHS and IEC 62474 DB Form/Declaration Type:

05/19/2022

Details for "SN74AHCT373PW"

Current Product Information

Ti part number		Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*	
	SN74AHCT373PW	NIPDAU	Level-1-260C-UNLIM	TI MAI AYSIA A/T	PW 20	4.4x6.5x1.15	74.4	

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homoge	neous Material Level	Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.120881	99.997518	999975	0.162399	1624
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000827	8	0.000001	0
Precious Metals	Silver	7440-22-4	0.000002	0.001654	17	0.000003	0
Sub-Total			0.120884	100	1000000	0.162403	1624
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.292428	80	800000	0.392866	3929
Thermoplastics	Ероху	85954-11-6	0.073107	20	200000	0.098216	982
Sub-Total			0.365535	100	1000000	0.491082	4911
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	27.85926	97.41	974100	37.42782	374278
Copper and Its Alloys	Iron	7439-89-6	0.6864	2.4	24000	0.922151	9222
Copper and Its Alloys	Phosphorus	7723-14-0	0.00858	0.03	300	0.011527	115
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00858	0.03	300	0.011527	115
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.00858	0.03	300	0.011527	115
Zinc and Its Alloys	Zinc	7440-66-6	0.0286	0.1	1000	0.038423	384
Sub-Total			28.6	100	1000000	38.422975	384230
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.437552	95.12	951200	0.587834	5878
Precious Metals	Gold	7440-57-5	0.003588	0.78	7800	0.00482	48
Precious Metals	Palladium	7440-05-3	0.01886	4.1	41000	0.025338	253
Sub-Total			0.46	100	1000000	0.617992	6180
Mold Compound	•					-	
Other Inorganic Materials	Fused Silica	60676-86-0	37.575008	86	860000	50.480545	504805
Other Plastics and Rubber	Carbon Black	1333-86-4	0.131076	0.300001	3000	0.176095	1761
Thermoplastics	Epoxy	85954-11-6	5.985786	13.7	137000	8.041668	80417
Sub-Total			43.69187	100	1000000	58.698309	586983
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.196343	100	1000000	1.60724	16072
Sub-Total			1.196343	100	1000000	1.60724	16072
Total			74.434632	·		100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

See Glossary of Terms for more details.

Important Part Information

T. There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

Ti bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. Ti may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. Il and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/19/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials.

Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

ROHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szg088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.